CLAIMS

1. A microelectronic circuit testing pack, comprising:

a portable supporting structure including first and second components for holding a substrate therebetween, the substrate carrying a microelectronic circuit and having a plurality of terminals connected to the microelectronic circuit;

a plurality of contacts on the second component, the contacts matching the terminals for making contact to the terminals;

a pressure differential cavity seal between the first and second components, the pressure differential cavity seal forming an enclosed pressure differential cavity together with surfaces of the first and second components;

a first passage formed through one of the first and second components, the first passage having a first opening at the pressure differential cavity and a second opening outside the pressure differential cavity;

a valve connected to the first passage, opening of the valve allowing a gas to flow through the first passage, and closing of the valve keeping the gas from flowing through the first passage;

a first interface, on the portable supporting structure and connected to the contacts, for connection to a second interface on a stationary structure when the portable supporting structure is removably held by the stationary structure; and

a securing system that includes a first securing assembly having:

a first part that engages with the first component;

a second part that engages with the second component; and

a connecting part having opposing ends secured to the first and second parts respectively to form a locking arrangement, wherein the locking arrangement rotates about an axis normal to the substrate between a locking position wherein the locking arrangement maintains the first and second components locked in a closed position and an unlocked position wherein the locking arrangement permits movement of the first and second components from a closed relationship into a spaced relationship.

2. The microelectronic circuit testing pack of claim 1, wherein the second securing assembly includes:

an engaging mechanism connected to the locking arrangement and operable to rotate the locking arrangement between the locking position and the unlocked position.

3. The microelectronic circuit testing pack of claim 2, wherein the engaging mechanism causes the second part to move between the locking position and the unlocked position.

4. The microelectronic circuit testing pack of claim 3, wherein the second part rotates between the locking position and the unlocked position.

5. The microelectronic circuit testing pack of claim 4, wherein the second part rotates about the axis.

6. The microelectronic circuit testing pack of claim 3, wherein the engaging mechanism includes a surface on the first part that forms a seat for contacting with a surface on a jaw of

a tool, the jaw of the tool being rotatable to rotate the first part and the first part rotating the second part through the connecting part to move between the locking position and the unlocked position.

7. The microelectronic circuit testing pack of claim 6, wherein the surface on the first part that forms the seat is an external surface of the first part.

8. The microelectronic circuit testing pack of claim 7, wherein the first part has a tool pin opening therein for aligning a pin of the tool with the first part.

9. The microelectronic circuit testing pack of claim 4, wherein the second part has a body and at least a first wing piece extending from the body, wherein the first wing piece moves over a shoulder of the second component when moving into a first locking position and off the shoulder when moving out of the first locking position towards the unlocked position.

10. The microelectronic circuit testing pack of claim 9, wherein the second part has a second wing piece extending from the body, wherein the second wing piece moves over the shoulder of the second component when moving into a second locking position and off the shoulder when moving out of the second locking position towards the unlocked position.

11. The microelectronic circuit testing pack of claim 10, wherein the securing system further includes:

a tuning block mounted in a stationary position relative to the second component, the tuning block having a levelling surface over which the second wing piece is located when the first wing piece is located over the shoulder, the second part being adjustable relative to the first part to adjust a gap between the levelling surface and the second wing piece.

12. The microelectronic circuit testing pack of claim 1, wherein the securing system further includes:

a locking nut that has thread that engages with a thread on the connecting part to adjust the second part rotationally relative to the connecting part.

13. The microelectronic circuit testing pack of claim 11, wherein the securing system further includes:

a shim between the tuning block and the first component, to adjust a distance between the levelling surface and the first component.

14. The microelectronic circuit testing pack of claim 11, wherein the securing system further includes:

a snap mechanism having a snap surface that snaps into a first snap depression to resist movement of the second part out of the locking position and into a second snap depression to resist movement of the second part out of the unlocked position.

15. The microelectronic circuit testing pack of claim 14, wherein the first and second snap depressions are located on the locking arrangement.

16. The microelectronic circuit testing pack of claim 15, wherein the first and second snap depressions are located on the second part.

17. The microelectronic circuit testing pack of claim 1, wherein the first component includes a backing plate and a signal distribution board, wherein a portion of the signal distribution board is located between the backing plate and the second component, the signal distribution board having an opening through which the connecting part is inserted, the opening having a first dimension on an axis towards a center point of the signal distribution board that is larger than a second dimension transverse to the axis, the connecting part having a first portion that is smaller than the first dimension in a direction of the axis to allow for thermal expansion of the signal distribution board and the backing plate relative to one another and the first portion being dimensioned to slidably fit within the second dimension of the opening to prevent movement of the signal distribution board in a direction transverse to the axis relative to the backing plate.

18. The microelectronic circuit testing pack of claim 17, wherein the connecting part has a second portion with a first thickness that can fit through the opening in the direction of the axis during said insertion and is larger than the second dimension of the opening, and a second thickness transverse to the first thickness that can fit through the second dimension of the opening during said insertion.

19. The microelectronic circuit testing pack of claim 1, wherein the securing system includes:

a second securing assembly, wherein each respective securing assembly having:

a first part that engages with the first component;

a second part that engages with the second component; and

a connecting part having opposing ends secured to the first and second parts respectively to form a locking arrangement, wherein the locking arrangement rotates about an axis normal to the substrate between a locking position wherein the locking arrangement maintains the first and second components locked in a closed position and an unlocked position wherein the locking arrangement permits movement of the first and second components from a closed relationship into a spaced relationship.

20. The microelectronic circuit testing pack of claim 19, wherein the second securing assembly includes:

an engaging mechanism connected to the locking arrangement and operable to rotate the locking arrangement between the locking position and the unlocked position.

21. The microelectronic circuit testing pack of claim 19, wherein the first and second securing assemblies have respective second parts that are on a same side of the second component.

22. The microelectronic circuit testing pack of claim 1, wherein the pressure differential cavity seal surrounds the contacts and the terminals.

23. The microelectronic circuit testing pack of claim 1, wherein the pressure differential cavity seal is secured to the second component when the first and second components are apart.

24. The microelectronic circuit testing pack of claim 1, wherein the pressure differential cavity seal is a lip seal.

25. The microelectronic circuit testing pack of claim 1, wherein the first passage is a pressure reduction passage, the first opening is an inlet opening, the second opening is an outlet opening, the valve is a pressure reduction valve, the gas is air allowed out of the pressure differential cavity to move the first and second components relatively towards one another for ensuring proper contact between the contacts and the terminals, and closing of the pressure reduction valve keeping air from entering the pressure differential cavity.

26. The microelectronic circuit testing pack of claim 25, wherein the pressure reduction valve is a pressure reduction check valve, a vacuum release passage being formed through a component having the pressure reduction check valve, the vacuum release passage having an inlet opening at the pressure differential cavity and an outlet opening outside the pressure differential cavity, further comprising:

a second valve, being a vacuum release valve connected to the vacuum release passage, opening of the vacuum release valve allowing air into the pressure differential cavity and closing of the vacuum release valve keeping air from escaping out of the pressure

differential cavity.

27. The microelectronic circuit testing pack of claim 1, wherein the substrate is a wafer with a plurality of microelectronic circuits.

28. The microelectronic circuit testing pack of claim 1, wherein the contacts are pins, each pin having a spring that is depressed against a spring force thereof when the respective contact is depressed by a respective one of the terminals.

29. A tester apparatus, comprising:

a portable supporting structure including first and second components for holding a substrate therebetween, the substrate carrying a microelectronic circuit and having a plurality of terminals connected to the microelectronic circuit;

a plurality of contacts on the second component, the contacts matching the terminals for making contact to the terminals;

a pressure differential cavity seal between the first and second components, the pressure differential cavity seal forming an enclosed pressure differential cavity together with surfaces of the first and second components;

a pressure reduction first passage formed through one of the first and second components, the pressure reduction first passage having an inleta first opening at the pressure differential cavity and an outleta second opening outside the pressure differential cavity;

a pressure reduction valve connected to the pressure reduction first passage, opening

of the pressure reduction valve allowing air out of a gas to flow through the first passage the pressure differential cavity to move the first and second components relatively towards one another for ensuring proper contact between the contacts and the terminals, and closing of the pressure reduction valve keeping air from flowing through the first passage entering the pressure differential cavity;

a first interface, on the portable supporting structure and connected to the contacts, for connection to a second interface on a stationary structure when the portable supporting structure is removably held by the stationary structure; and

a securing system that includes a first securing assembly having:

a first part that engages with the first component;

a second part that engages with the second component; and

a connecting part having opposing ends secured to the first and second parts respectively to form a locking arrangement; a stationary structure, the portable supporting structure being receivable to be held by the stationary structure and being removable from the stationary structure, wherein the locking arrangement rotates about an axis normal to the substrate between a locking position wherein the locking arrangement maintains the first and second components locked in a closed position and an unlocked position wherein the locking arrangement permits movement of the first and second components from a closed relationship into a spaced relationship;

a second interface on the stationary structure, the second interface being connected to the first interface when portable supporting structure is held by the stationary structure, and being disconnected from the first interface when the portable supporting structure is removed from the stationary structure; and

an electrical tester connected through the second interface, the first interface, and the contacts to the terminals so that signals are transmitted between the electrical tester and the microelectronic circuit to test the microelectronic circuit.

30. A method of testing a microelectronic circuit held by a substrate, comprising:

holding the substrate between first and second components of a portable supporting structure, the second component having contacts against terminals of the substrate connected to the microelectronic circuit, wherein a first passage is formed through one of the first and second components, the first passage having a first opening at a pressure differential cavity and a second opening outside the pressure differential cavity;

locating a pressure differential cavity seal between the first and second components to form an enclosed cavity by surfaces of the first and second components and the pressure differential cavity seal;

opening a valve to allow a gas to flow through the first passage;

closing the valve, keeping the gas from flowing through the first passage;

rotating a locking arrangement from an unlocked position wherein the locking arrangement permits movement of the first and second components from a closed relationship into a spaced relationship into a locking position wherein the locking arrangement maintains the first and second components locked in the closed position, the locking arrangement including:

a first part that engages with the first component;

a second part that engages with the second component;

a connecting part having opposing ends secured to the first and second parts respectively to form a locking arrangement, wherein the locking arrangement rotates about an axis normal to the substrate between a locking position wherein the locking arrangement maintains the first and second components locked in a closed position and an unlocked position wherein the locking arrangement permits movement of the first and second components from a closed relationship into a spaced relationship;

receiving the portable supporting structure by a stationary structure with a first interface on the portable supporting structure connected to a second interface on the stationary structure;

transmitting signals between an electrical tester and the microelectronic circuit through the terminals, contacts, and first and second interfaces to test the microelectronic circuit;

removing the portable supporting structure from the stationary structure; and

rotating the locking arrangement from the locking position wherein the locking arrangement maintains the first and second components locked in the closed position into the unlocked position wherein the locking arrangement permits movement of the first and second components from the closed relationship into the spaced relationship.